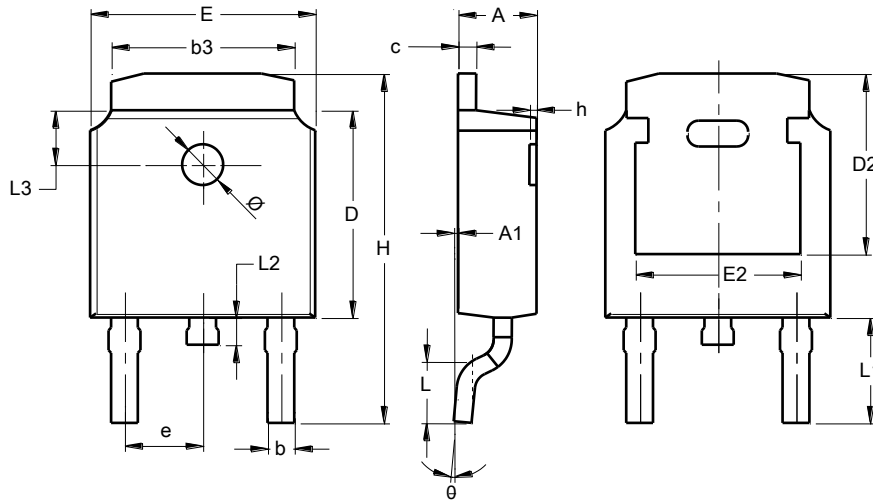


Package Outline Dimensions

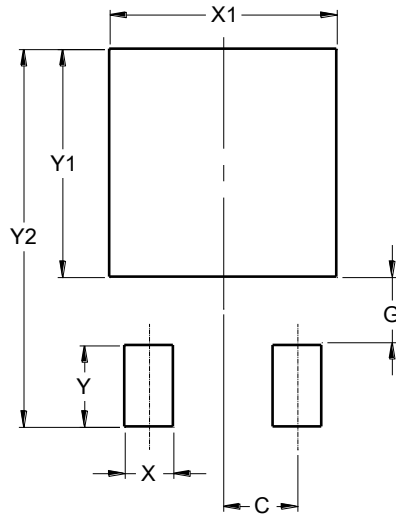
TO252 (Type CJ)



TO252 (Type CJ)			
Dim	Min	Max	Typ
A	2.200	2.400	--
A1	0.000	0.127	--
b	0.635	0.770	--
b3	5.100	5.460	--
c	0.460	0.580	--
D	6.000	6.200	--
D2	5.250 REF		
E	6.500	6.700	--
E2	4.830 REF		
e	2.186	2.386	--
h	0.000	0.300	--
H	9.712	10.312	--
L	1.400	1.700	--
L1	2.900 REF		
L2	0.600	1.000	--
L3	1.600 REF		
Ø	1.100	1.300	--
θ	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

TO252 (Type CJ)



Dimensions	Value (in mm)
C	2.300
G	2.100
X	1.500
X1	7.000
Y	2.500
Y1	7.000
Y2	11.600

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

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